

#44/4-26-02  
Congress Mail Label: EV 001687798 US  
Date of Deposit: November 13, 2001

In re Patent Application of: : Docket: YOR919990336US2  
Chao-kun Hu et al. : Prior Group Art Unit: 2815  
Serial No.: To be Assigned : Prior Examiner: A. Wilson  
Filed: Herewith : Date: November 13, 2001  
For: REDUCED ELECTROMIGRATION AND STRESSED INDUCED MIGRATION  
OF Cu WIRES BY SURFACE COATING

11002 U.S. PTO  
10/054605  
11/13/01

INFORMATION DISCLOSURE STATEMENT  
PURSUANT TO 37 C.F.R. §1.98(d)

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Pursuant to applicants' duty of disclosure under 37 C.F.R. §1.56 and consistent with 37 C.F.R. §§1.97 and 1.98, submitted herewith is a Form PTO-1449 listing references that may be material to the above-captioned application.

The listed references were previously cited by or submitted to the Patent and Trademark Office in prior parent application, U.S. Serial No. 09/361,573, filed July 27, 1999, reliance upon which for an earlier effective filing date is claimed under 35 U.S.C. §120. Accordingly, pursuant to 37 C.F.R. §1.98(d) copies of said references are not enclosed herewith.

This information Disclosure Statement is being submitted concurrently at filing, thus no fee or certification under 37 C.F.R. §1.97 is required.

Respectfully submitted,  
Attorney for the Applicant(s)

by Robert M. Trepp  
Robert M. Trepp  
Reg. No.: 25,933

IBM Corporation  
Intellectual Property Law Department  
P. O. Box 218  
Yorktown Heights, N. Y. 10598  
Telephone No.: (914) 945-3147  
Fax No.: (914) 945-3281